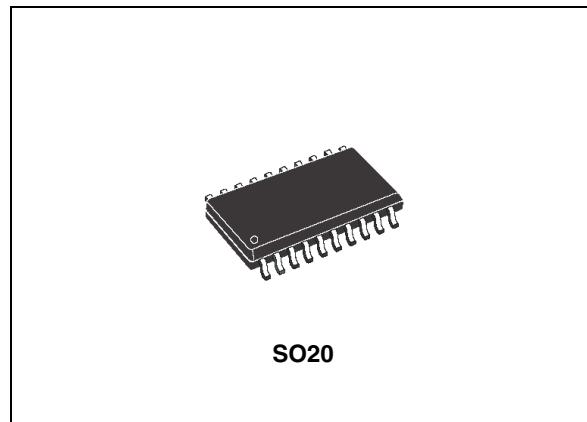


0.5 A high side driver intelligent power switch

Features

- 0.5 A output current
- 8 V to 35 V supply voltage range
- Internal current limiting
- Thermal shutdown
- Open ground protection
- Internal negative voltage clamping for fast demagnetization
- Differential inputs with large common mode range and threshold hysteresis
- Undervoltage lockout with hysteresis
- Open load detection
- Two diagnostic outputs
- Output status LED driver
- Non-dissipative short-circuit protection
- Immunity against burst transient (IEC 61000-4-4)
- ESD protection (human body model $\pm 2\text{ kV}$)



Description

The L6375D is a monolithic intelligent power switch in BCDmultipower technology, for driving inductive or resistive loads with controlled output voltage slew rate and short-circuit protection.

An internal clamping diode enables the fast demagnetization of inductive loads. Diagnostics for CPU feedback and extensive use of electrical protection make this device extremely rugged and specially suitable for industrial automation applications.

Table 1. Device summary

| Order codes | Op. temp. range | Package | Packaging |
|-------------|-----------------|---------|---------------|
| L6375D | -25 to +125 °C | SO20 | Tube |
| L6375DTR | | | Tape and reel |

Contents

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1 Block diagram and pin description

Figure 1. Block diagram

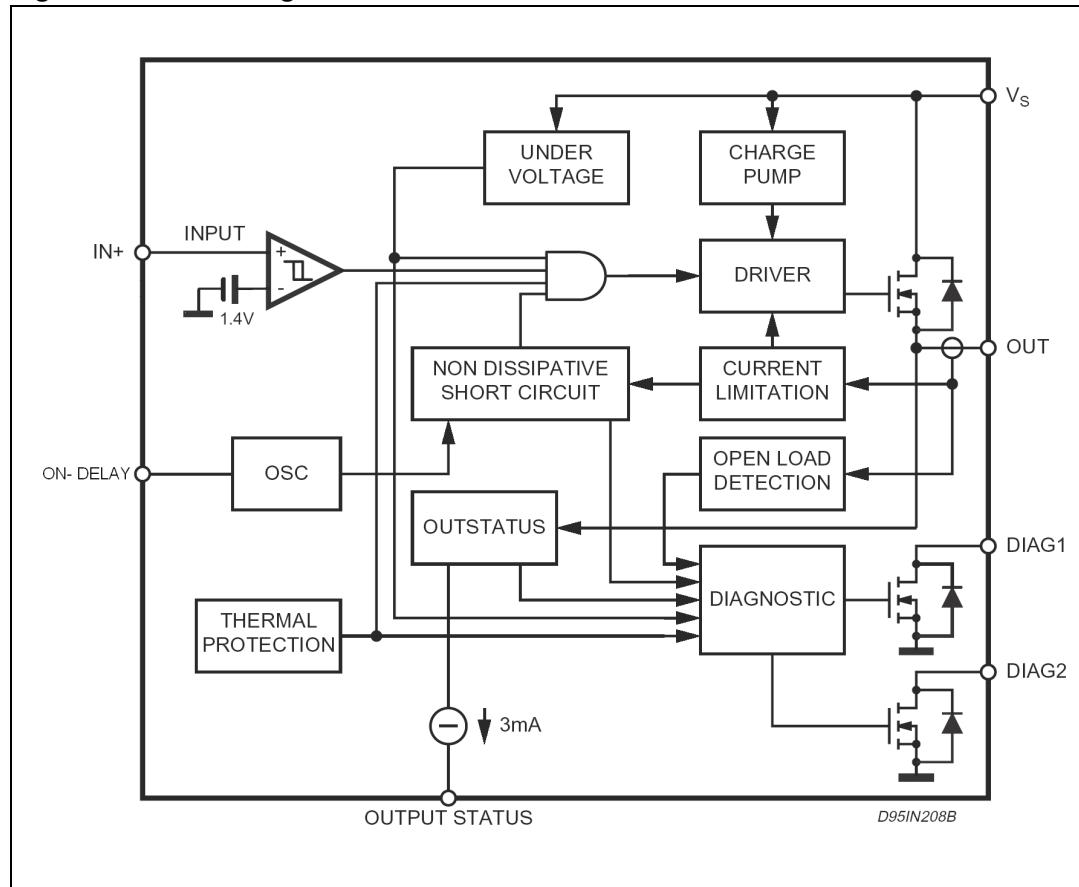
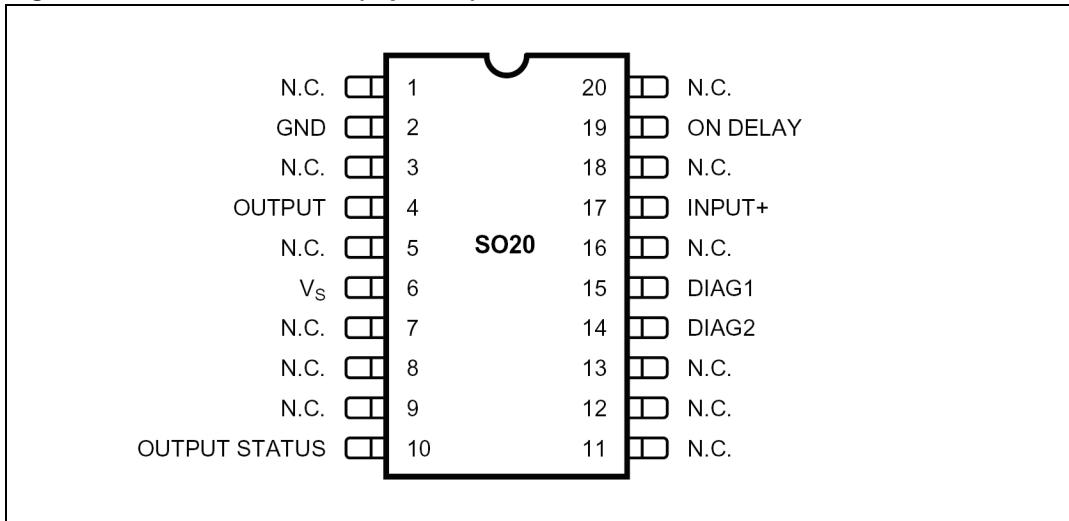


Figure 2. Pin connection (top view)

1.1 Pin description

Table 2. Pin description

| Pin n° | Pin name | Function |
|--|----------------|--|
| 2 | GND | Ground |
| 4 | OUT | High side output with built-in current limitation |
| 6 | V _S | Supply voltage input; the value of the supply voltage is monitored to detect undervoltage condition |
| 10 | Output status | This current source output is capable of driving an LED to signal the status of the output pin. The pin is active (source current) when the output pin is considered high (see <i>Figure 4</i>) |
| 15 | DIAG1 | DIAGNOSTIC 1 output. This open drain reports the IC working conditions (see <i>Table 6: Diagnostic truth table</i>) |
| 14 | DIAG2 | DIAGNOSTIC 2 output. This open drain reports the IC working conditions (see <i>Table 6: Diagnostic truth table</i>) |
| 17 | IN+ | Comparator inverting input |
| 19 | ON-DELAY | Programmable ON time interval duration during short-circuit operation |
| 1, 3, 5, 7, 8, 9, 11, 12, 13, 16, 18, 20 | N.C. | Not connected |

2 Electrical specifications

2.1 Absolute maximum ratings

Table 3. Absolute maximum ratings

| Symbol | Parameter | Value | Unit |
|-----------------|---|--------------------|------|
| V_S | Supply voltage ($t_w < 10 \text{ ms}$) | 50 | V |
| V_S | Supply voltage (DC) | 40 | V |
| $V_S - V_{out}$ | Supply to output differential voltage | Internally limited | V |
| V_{od} | Externally forced voltage | -0.3 to 7 | V |
| I_{od} | Externally forced current | ± 1 | mA |
| I_{out} | Output current (see also I_{sc}) | Internally limited | A |
| V_{out} | Output voltage | Internally limited | V |
| P_{TOT} | Power dissipation | Internally limited | W |
| V_{diag} | External voltage | -0.3 to 40 | V |
| I_{diag} | Externally forced current | -10 to 10 | mA |
| I_i | Input current | 20 | mA |
| V_i | Input voltage | -10 to $V_S + 0.3$ | V |
| T_{op} | Ambient temperature, operating range | -25 to 85 | °C |
| T_J | Junction temperature, operating range (see Section 2.6) | -25 to 125 | °C |
| T_{STG} | Storage temperature | -55 to 150 | °C |
| E_I | Energy inductive load $T_J = 85 \text{ °C}$ | 200 | mJ |

2.2 Thermal data

Table 4. Thermal data

| Symbol | Parameter | Value | Unit |
|------------|---|-------|------|
| R_{thJA} | Thermal resistance junction-ambient max. ⁽¹⁾ | 65 | °C/W |
| R_{thJP} | Thermal resistance junction-pins max. | 15 | °C/W |

1. When mounted on an FR4 printed circuit board with 0.5 cm² of Cu (at least 35 mm thick).

2.3 Electrical characteristics

$V_S = 24 \text{ V}$; $T_J = -25 \text{ to } +125 \text{ }^\circ\text{C}$, unless otherwise specified.

Table 5. Electrical characteristics

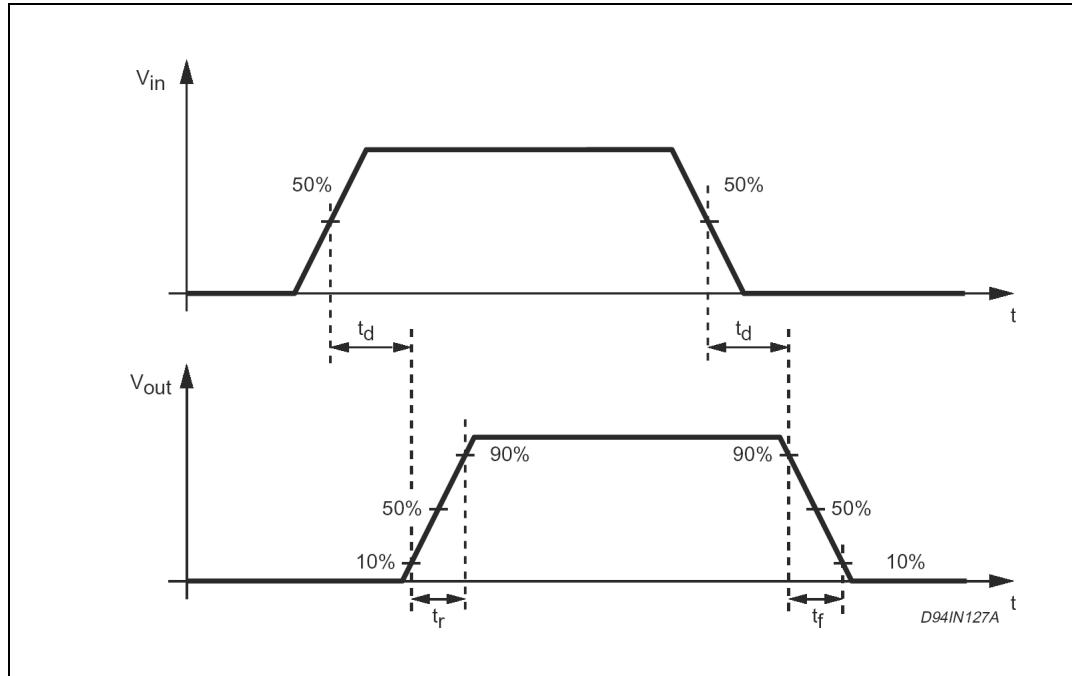
| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Unit |
|------------|--|--|------|--------------------------|--------------------------|----------------------|
| V_{smin} | Supply voltage for valid diagnostic | $I_{diag} = > 0.5 \text{ mA}; V_{diag} = 1.5 \text{ V};$ | 4 | | 35 | V |
| V_S | Operative supply voltage | | 8 | 24 | 35 | V |
| V_{sth1} | Undervoltage threshold 1 | | 7 | 7.5 | 8 | V |
| V_{sth2} | Undervoltage threshold 2 | | 6.5 | 7 | 7.5 | V |
| V_{shys} | Undervoltage hysteresis | | 300 | 500 | 700 | mV |
| I_q | Quiescent current | Output open | | 800 | | μA |
| I_{qo} | Quiescent current | Output ON | | 1.6 | | mA |
| V_{ith} | Input threshold voltage | | 0.8 | 1.3 | 2 | V |
| V_{iths} | Input threshold hysteresis | | 50 | | 400 | mV |
| V_{il} | Input low level voltage | | -7 | | 0.8 | V |
| V_{ih} | Input high level voltage | $V_S < 18 \text{ V}$ | 2 | | $V_S - 3$ | V |
| V_{ih} | Input high level voltage | $V_S > 18 \text{ V}$ | 2 | | 15 | V |
| I_{ib} | Input bias current | $V_i = -7 \text{ to } 15 \text{ V}$ | -250 | | 250 | μA |
| I_{dch} | Delay capacitor charging current | ON DELAY pin shorted to ground | | 2.5 | | μA |
| V_{don} | Output voltage drop | $I_{out} = 500 \text{ mA } T_J = 25 \text{ }^\circ\text{C}$ $T_J = 125 \text{ }^\circ\text{C}$ $I_{out} = 625 \text{ mA } T_J = 25 \text{ }^\circ\text{C}$ $T_J = 125 \text{ }^\circ\text{C}$ | | 200 320 250 400 | 280 440 350 550 | mV mV mV mV |
| I_{olk} | Output leakage current | $V_i = \text{LOW}; V_{out}=0$ | | | 100 | μA |
| V_{ol} | Output low state voltage | $V_i = \text{HIGH}; \text{pin floating}$ | | 0.8 | 1.5 | V |
| V_{cl} | Internal voltage clamp ($V_S - V_{out}$) | $I_o = 200 \text{ mA}$ single pulsed = 300 ms | 48 | 53 | 58 | V |
| I_{sc} | Short-circuit output current | $V_S = 8 \text{ to } 35 \text{ V}; R_i = 2 \Omega;$ | 0.75 | 1.1 | 1.5 | A |
| I_{old} | Open load detection current | $V_i = V_{ih}; T_A = 0 \text{ to } +85 \text{ }^\circ\text{C}$ | 1 | 3 | 6 | mA |
| V_{oth1} | Output status threshold 1 voltage | | 4.5 | 5 | 5.5 | V |
| V_{oth2} | Output status threshold 2 voltage | | 4 | 4.5 | 5 | V |
| V_{ohys} | Output status threshold hysteresis | | 300 | 500 | 700 | mV |
| I_{osd} | Output status source current | $V_{out} > V_{oth1}; V_{os} = 2.5 \text{ V}$ | 2 | | 4 | mA |

Table 5. Electrical characteristics (continued)

| Symbol | Parameter | Test condition | Min. | Typ. | Max. | Unit |
|---|--|--|-------------|-------------|-------------|-------------------------|
| V_{osd} | Active output status driver drop voltage | $V_S - V_{os} = 2 \text{ mA}$ $T_A = 0 \text{ to } +85^\circ\text{C}$ | | 1.5 | 3 | V |
| I_{oslk} | Output status driver leakage current | $V_{out} < V_{oth2}; V_{os} = 0 \text{ V}$ $V_S = 18 \text{ to } 35 \text{ V}$ | | 25 | | mA |
| V_{dgl} | Diagnostic drop voltage | $D1 / D2 = L; I_{diag} = 0.5 \text{ mA}$ $D1 / D2 = L; I_{diag} = 3 \text{ mA}$ | | 40 250 | | mV mV |
| I_{dglk} | Diagnostic leakage current | $D1 / D2 = H; 0 < V_{dg} < V_S$ $V_S = 15.6 \text{ to } 35 \text{ V}$ | | | 5 | μA |
| T_{max} | Overtemperature upper threshold | | | 150 | | $^\circ\text{C}$ |
| T_{hys} | Overtemperature hysteresis | | | 20 | | $^\circ\text{C}$ |
| AC operation (pin numbering referred to Minidip package) | | | | | | |
| $t_r - t_f$ | Rise or fall time | $V_S = 24 \text{ V}; R_l = 70 \Omega$ R_l to ground | | 20 | | μs |
| t_d | Delay time | $V_S = 24 \text{ V}; R_l = 70 \Omega$ R_l to ground | | 5 | | μs |
| dV/dt | Slew-rate (rise and fall edge) | | 0.7 | 1 | 1.5 | $\text{V}/\mu\text{s}$ |
| t_{ON} | ON time during short-circuit condition | $50 \text{ pF} < C_{DON} < 2 \text{ nF}$ | | 1.28 | | $\mu\text{s}/\text{pF}$ |
| t_{OFF} | OFF time during short-circuit condition | | | 64 | | t_{ON} |
| f_{max} | Maximum operating frequency | | | 25 | | KHz |
| Source drain NDMOS diode | | | | | | |
| V_f | Forward ON voltage | @ $I_{fsd} = 625 \text{ mA}$ | | 1 | 1.5 | V |
| I_{fD} | Forward peak voltage | $t = 10 \text{ ms}; d = 20\%$ | | 2 | | A |
| t_{rr} | Reverse recovery time | $I_f = 625 \text{ mA}$ $di/dt = 25 \text{ A/ms}$ | 200 | | | ns |
| t_{fr} | Forward recovery time | | | 50 | | ns |

2.4 Switching waveform

Figure 3. Switching waveform



2.5 Input section

A single ended input TTL/CMOS compatible with a wide voltage range and high noise immunity (thanks to a built-in hysteresis) is available.

2.6 Overtemperature protection (OVT)

An on-chip overtemperature protection provides excellent protection of the device in extreme conditions. Whenever the temperature, measured on a central portion of the chip, exceeds $T_{max} = 150^{\circ}\text{C}$ (typical value), the device is shut off, and the DIAG2 output goes LOW. Normal operation is resumed as the chip temperature (normally after a few seconds) falls below $T_{max} - T_{hys} = 130^{\circ}\text{C}$ (typical value). The hysteresis avoids that an intermittent behavior takes place.

2.7 Undervoltage protection (UV)

The supply voltage is expected to range from 8 to 35 V. In this range the device operates correctly. To avoid any malfunctioning the supply voltage is continuously monitored to provide an undervoltage protection. As V_S falls below $V_{sth} - V_{shys}$ (typically 7.5 V, see [Figure 1](#)) the output Power MOSFET is switched off and DIAG1 and DIAG2 (see [Section 2.11](#)). Normal operation is resumed as soon as V_S exceeds V_{sth} . The hysteretic behavior prevents intermittent operation at low supply voltage.

2.8 Overcurrent operation

In order to implement a short-circuit protection the output Power MOSFET is driven in linear mode to limit the output current to the I_{sc} (1.1 A typical value). This condition (current limited to the I_{sc} value) lasts for a T_{on} time interval, that can be set by means of a capacitor (C_{don}) connected to the ON DELAY pin according to the following formula:

$$T_{on} = 1.28 \mu\text{sec}/\text{pF}$$

for

$$50 \text{ pF} < C_{don} < 2 \text{ nF}$$

After the T_{on} interval has expired the output Power MOSFET is switched off for the T_{off} time interval with:

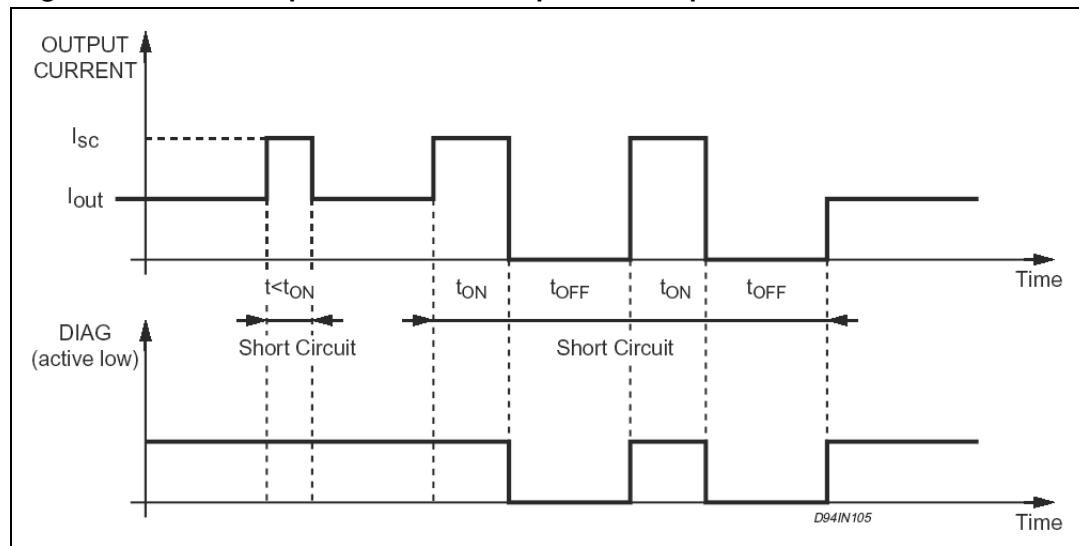
$$T_{off} = 64 \cdot T_{on}$$

When also the T_{off} interval has expired, the output Power MOSFET is switched ON. At this point in time two conditions may occur

- a) The overload is still present, and then the output Power MOSFET is again driven in linear mode (limiting the output current to I_{sc}) for another T_{on} , starting a new cycle, or
- b) the overload condition is removed, and the output Power MOSFET is no longer driven in linear mode. All these occurrences are presented on the DIAG2 pin (see [Figure 2](#)).

This unique feature is called non-dissipative short-circuit protection and it ensures a very safe operation even in permanent overload conditions. Note that choosing the most appropriate value for the T_{on} interval (i.e. the value of the C_{don} capacitor) a delay (the T_{on} itself) prevents that misleading short-circuit information is presented on the DIAG2 output, when driving capacitive loads (that acts as a short-circuit in the very beginning) or incandescent lamp (a cold filament has a very low resistive value). The non-dissipative short-circuit protection can be disabled (keeping $T_{on} = 0$ but with the output current still limited to I_{sc} , and diagnostic disabled) simply shorting to ground the ON DELAY pin.

Figure 4. Non-dissipative short-circuit protection operation



2.9 Diagnostic logic

The operating conditions of the device are permanently monitored and the following occurrences are signalled via the DIAG1/DIAG2 open drain output pins, see *Table 6: Diagnostic truth table*.

- Short-circuit vs. ground
- Short-circuit vs. VS
- Undervoltage (UV)
- Overtemperature (OVT)
- Open load, if the output current is less than 3 mA (typical value).

2.10 Demagnetization of inductive loads

An internal Zener diode, limiting the voltage across the Power MOSFET to between 50 and 60 V (V_{cl}), provides safe and fast demagnetization of inductive loads without external clamping devices. The maximum energy that can be absorbed from an inductive load is specified as 200 mJ (at $T_J = 85^\circ\text{C}$).

2.11 Diagnostic truth table

Table 6. Diagnostic truth table

| Diagnostic conditions | Input | Output | Diag1 | Diag2 |
|--|-------|--------|-------|-------|
| Normal operation | L | L | H | H |
| | H | H | H | H |
| Open load condition ($I_o < I_{old}$) | L | L | H | H |
| | H | H | L | H |
| Short to Vs | L | H | L | H |
| | H | H | L | H |
| Short-circuit to ground ($I_O = I_{sc}$) ⁽¹⁾ (pin ON-DELAY grounded) | H | X | H | H |
| | L | L | H | H |
| Output DMOS open | L | L | H | H |
| | H | L | L | H |
| Overtemperature | L | L | H | L |
| | H | L | H | L |
| Supply undervoltage ($V_S < V_{sth2}$) | L | L | L | L |
| | H | L | L | L |

1. A cold lamp filament, or a capacitive load may activate the current limiting circuit of the IPS, when the IPS is initially turned on.

3 Application circuits

Figure 5. Inductive load equivalent circuit

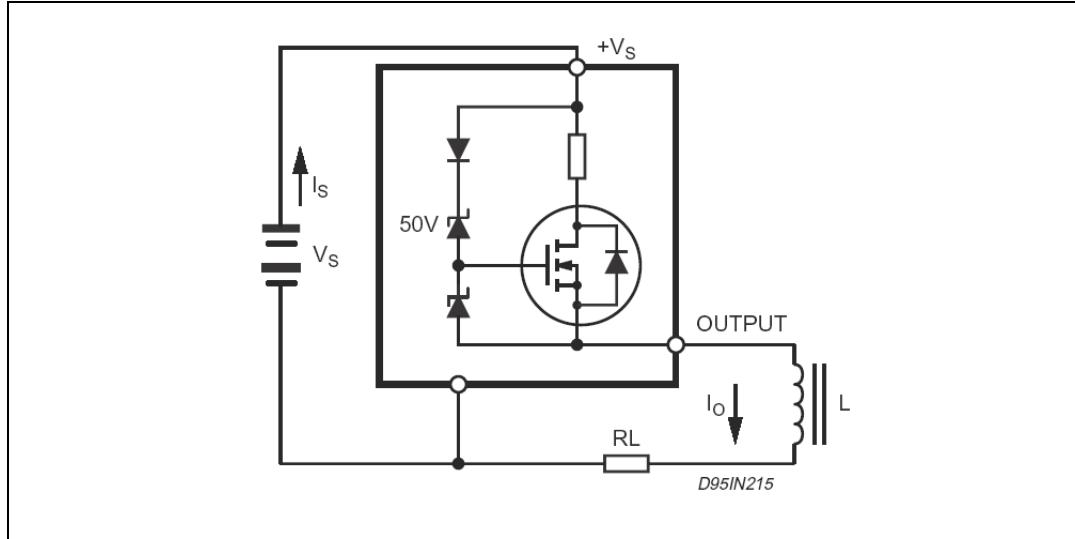


Figure 6. External demagnetization circuit (vs. ground)

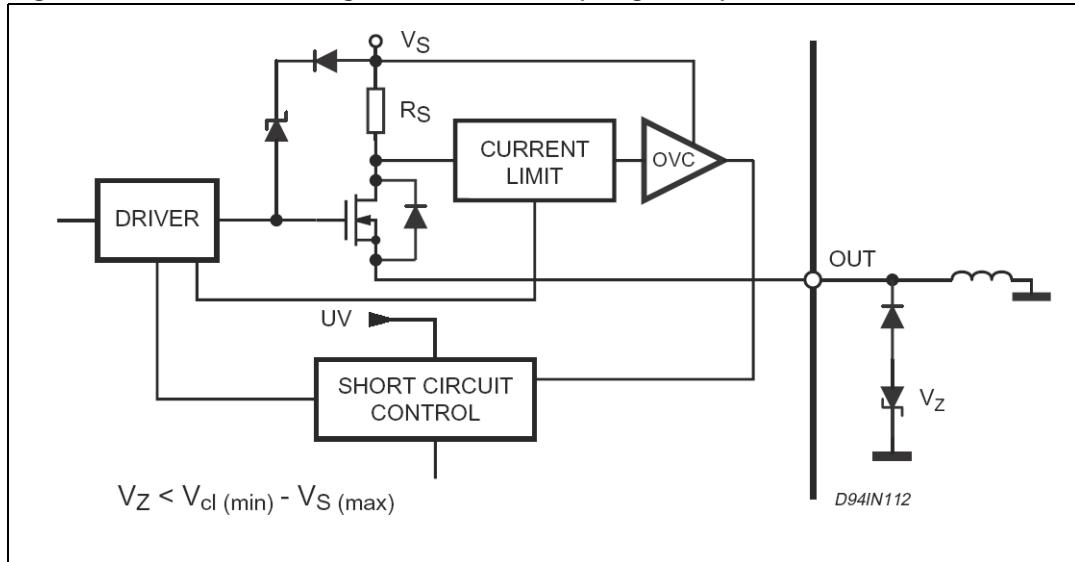
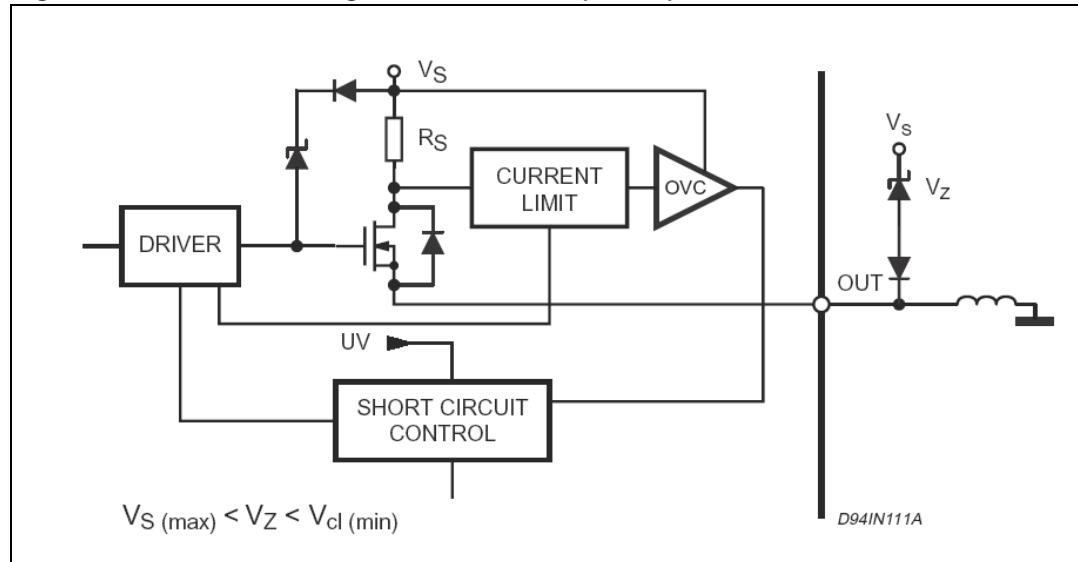
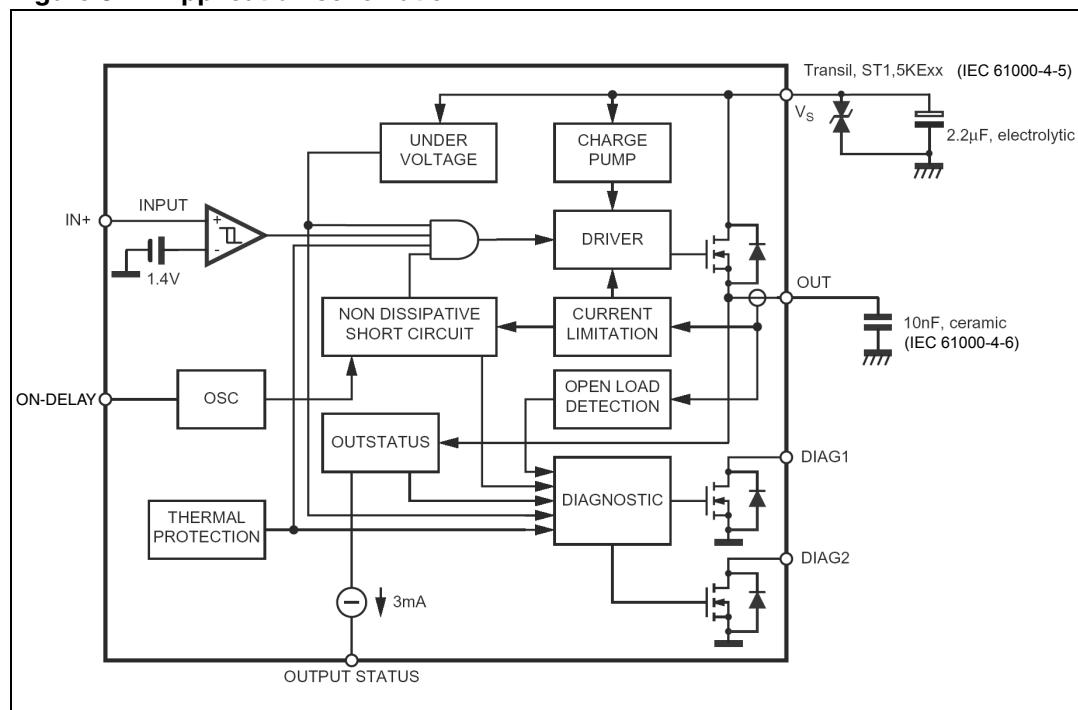


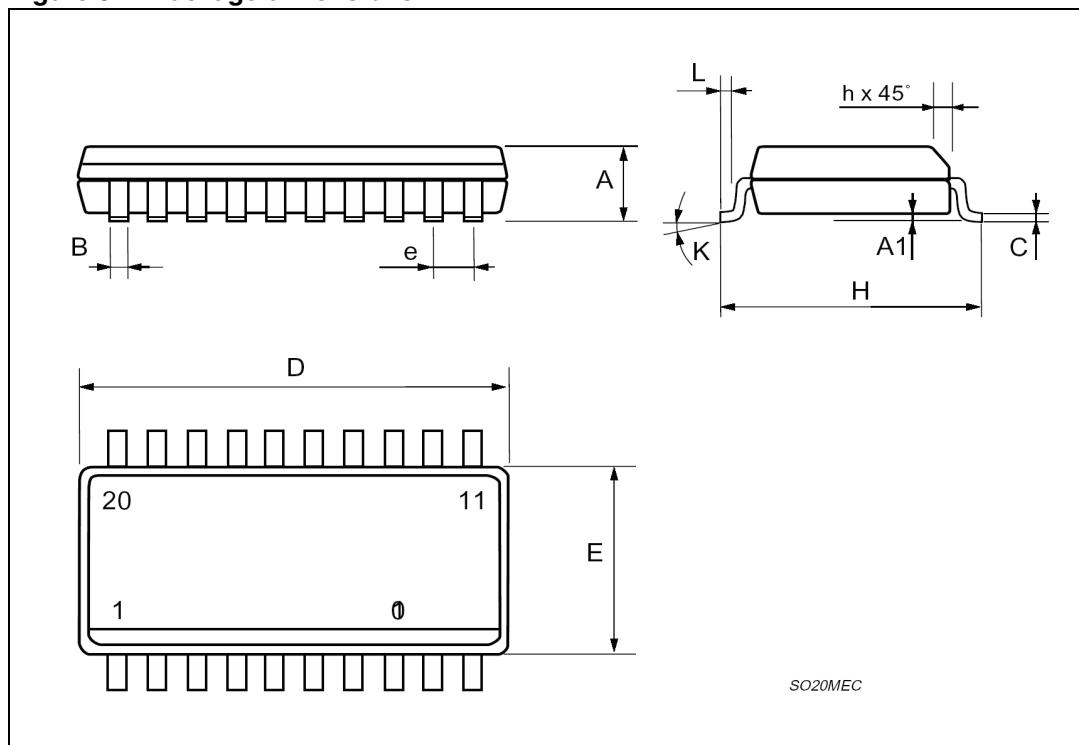
Figure 7. External demagnetization circuit (vs. VS)**Figure 8. Application schematic**

4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com.
ECOPACK is an ST trademark.

Table 7. SO20 mechanical data

| Dim. | mm | | | inch | | |
|------|---------------------|------|-------|-------|-------|-------|
| | Min. | Typ. | Max. | Min. | Typ. | Max. |
| A | 2.35 | | 2.65 | 0.093 | | 0.104 |
| A1 | 0.1 | | 0.3 | 0.004 | | 0.012 |
| B | 0.33 | | 0.51 | 0.013 | | 0.020 |
| C | 0.23 | | 0.32 | 0.009 | | 0.013 |
| D | 12.6 | | 13 | 0.496 | | 0.512 |
| E | 7.4 | | 7.6 | 0.291 | | 0.299 |
| e | | 1.27 | | | 0.050 | |
| H | 10 | | 10.65 | 0.394 | | 0.419 |
| h | 0.25 | | 0.75 | 0.010 | | 0.030 |
| L | 0.4 | | 1.27 | 0.016 | | 0.050 |
| K | 0° (min.) 8° (max.) | | | | | |

Figure 9. Package dimensions

5 Revision history

Table 8. Document revision history

| Date | Revision | Changes |
|-------------|----------|---|
| 24-Jul-2007 | 1 | Initial release |
| 29-Jun-2009 | 2 | Updated Table 5 on page 7 |
| 21-Dec-2011 | 3 | Updated Table 5 on page 7 |

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